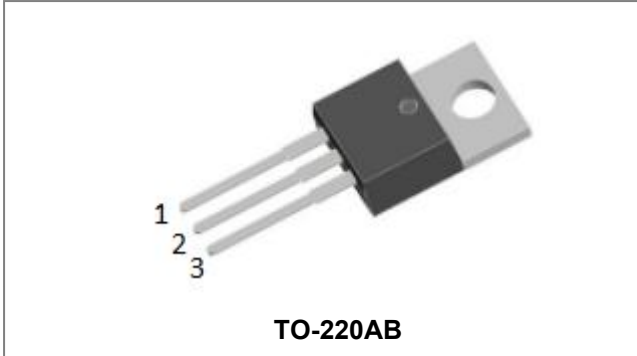


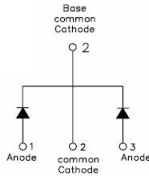
MBR10200CT SCHOTTKY RECTIFIER



Features

- 150°C T_J operation
- Center tap configuration
- Low forward voltage drop
- High purity, high temperature epoxy encapsulation for enhanced mechanical strength and moisture resistance
- High frequency operation
- Guard ring for enhanced ruggedness and long term reliability
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

Circuit Diagram



Applications

- Switching power supply
- Converters
- Free-Wheeling diodes
- Reverse battery protection

Maximum Ratings:

| Characteristics | Symbol | Condition | Max. | Units |
|--|--|---|------------------------------|-------|
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | V _{RRM} V _{RWM} V _R | - | 200 | V |
| Average Rectified Forward Current | I _{F(AV)} | 50% duty cycle @T _c =105°C, rectangular wave form | 5(Per Leg) 10(Per Device) | A |
| Peak One Cycle Non-Repetitive Surge Current(Per Leg) | I _{FSM} | 8.3ms, Half Sine pulse | 128 | A |

Electrical Characteristics:

| Characteristics | Symbol | Condition | Typ. | Max. | Units |
|-------------------------------------|-----------------|---|--------|--------|-------|
| Forward Voltage Drop (per leg) * | V _{F1} | @ 5 A, Pulse, T _J = 25 °C | 0.86 | 0.98 | V |
| | V _{F2} | @ 5 A, Pulse, T _J = 125 °C | 0.71 | 0.78 | V |
| Reverse Current (per leg) * | I _{R1} | @V _R = rated V _R T _J = 25 °C | 0.0001 | 1 | mA |
| Reverse Current (per leg) * | I _{R2} | @V _R = rated V _R T _J = 125 °C | 0.05 | 7 | mA |
| Junction Capacitance (per leg) | C _T | @V _R = 5V, T _C = 25 °C f _{SIG} = 1MHz | 80 | 150 | pF |
| Voltage Rate of Change | dv/dt | - | - | 10,000 | V/μs |

* Pulse width < 300 μs, duty cycle < 2%

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- <http://www.smc-diodes.com> - sales@smc-diodes.com •

Thermal-Mechanical Specifications:

| Characteristics | Symbol | Condition | Specification | Units |
|--|-----------------|---|---------------|-----------------------------|
| Junction Temperature | T_J | - | -55 to +150 | $^{\circ}\text{C}$ |
| Storage Temperature | T_{stg} | - | -55 to +150 | $^{\circ}\text{C}$ |
| Typical Thermal Resistance Junction to Case(Per leg) | $R_{\theta JC}$ | DC operation | 3.5 | $^{\circ}\text{C}/\text{W}$ |
| Typical Thermal Resistance Junction to Case(Per package) | $R_{\theta JC}$ | DC operation | 1.75 | $^{\circ}\text{C}/\text{W}$ |
| Typical Thermal Resistance, Case to Heat Sink | $R_{\theta CS}$ | Mounting surface, smooth and greased(only for TO-220) | 0.50 | $^{\circ}\text{C}/\text{W}$ |
| Approximate Weight | wt | - | 2 | g |
| Case Style | TO-220AB | | | |

Ratings and Characteristics Curves

Figure 1
Typical Forward Characteristics

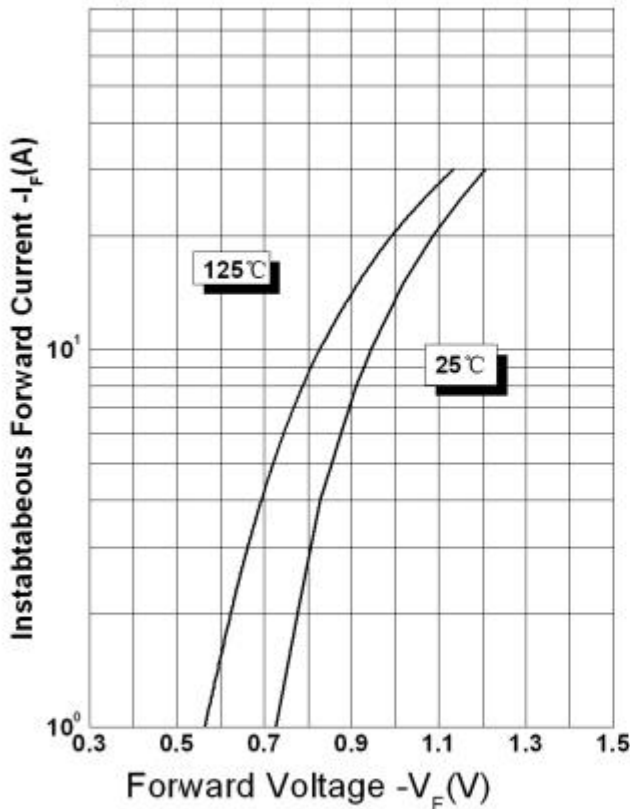


Figure 2
Typical Reverse Characteristics

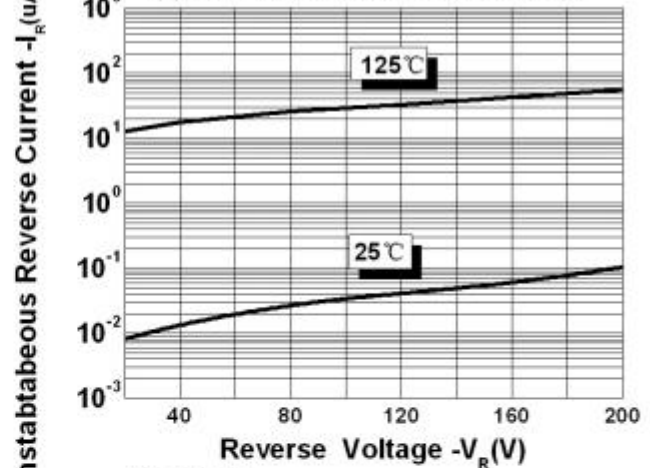
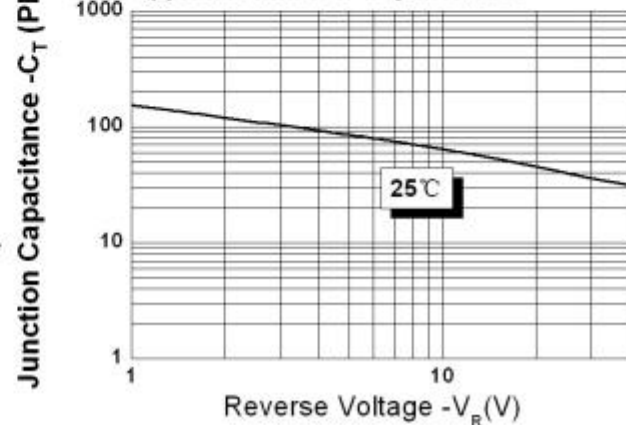
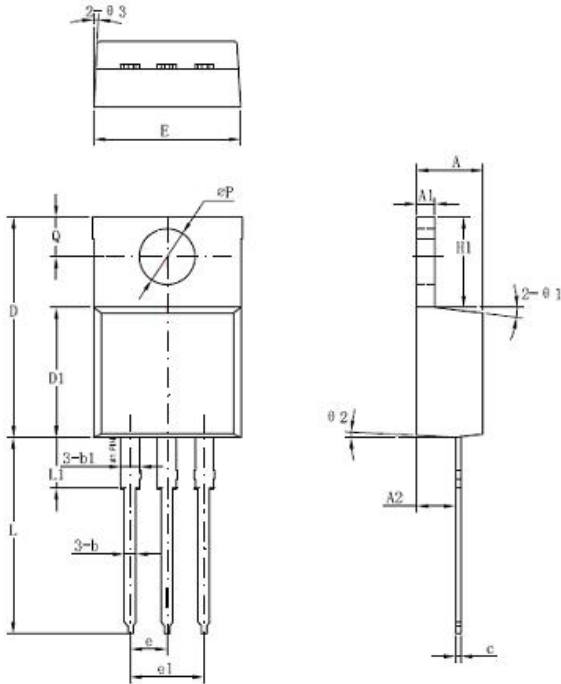


Figure 3
Typical Junction Capacitance

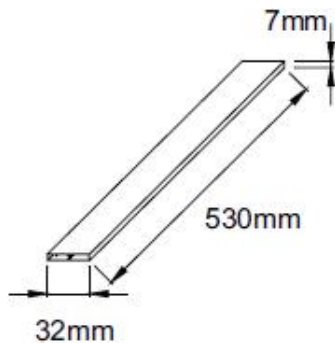


Mechanical Dimensions TO-220AB

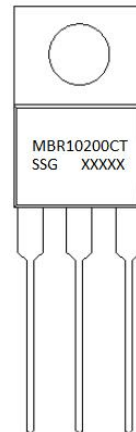


| Symbol | Dimensions in millimeters | | |
|--------|---------------------------|---------|-------|
| | Min | Typical | Max |
| A | 4.42 | 4.57 | 4.72 |
| A1 | 1.17 | 1.27 | 1.37 |
| A2 | 2.52 | 2.69 | 2.89 |
| b | 0.71 | 0.81 | 0.96 |
| b1 | 1.17 | 1.27 | 1.37 |
| c | 0.31 | 0.38 | 0.61 |
| D | 14.94 | 15.24 | 15.54 |
| D1 | 8.85 | 9.00 | 9.15 |
| E | 10.01 | 10.16 | 10.31 |
| e | | 2.54 | |
| e1 | 4.98 | 5.06 | 5.18 |
| H1 | 6.04 | 6.24 | 6.44 |
| L | 12.7 | 13.56 | 13.80 |
| L1 | 3.56 | 3.5 | 3.96 |
| ΦP | 3.74 | 3.84 | 4.04 |
| Q | 2.54 | 2.74 | 2.94 |
| Θ1 | | 7° | |
| Θ2 | | 3° | |
| Θ3 | | 4° | |

Tube Specification



Marking Diagram



Where XXXXX is YYWWL

MBR = Device Type
10 = Forward Current (10A)
200 = Reverse Voltage(200V)
CT = Configuration
SSG = SSG
YY = Year
WW = Week
L = Lot Number

Cautions: Molding resin
Epoxy resin UL:94V-0

Ordering Information

| Device | Package | Shipping |
|------------|--------------------|--------------|
| MBR10200CT | TO-220AB (Pb-Free) | 50 pcs/ tube |

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

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